

## Features



- Solid one-piece forged aluminum construction for maximum thermal conductivity.
- Pin fin design maximizes surface area and provides omni-directional cooling to eliminate concerns about orientation of the heat sink (unlike a linear extrusion).
- Precision-machined flat base ensures consistent contact between the heat sink, interface and LED substrate to maximize heat transfer.
- Standard 10mm base thickness allows for full recommended depth for mounting holes.

## Specifications

Model	Diameter (mm)	Height (mm)	Base Thickness (mm)	Weight (g)	Thermal Resistance (°C/W)	Power Dissipation (w)*	
						Ambient 25°C	Ambient 35°C
CPL5050-XXX	51	50	10	86	2.90	26	22
CPL5070-XXX	51	70	10	104	2.45	31	26

## Notes

- Thermal testing is performed in open air. Results in a closed environment will vary. Cooliance recommends that each application be tested.
- \*Power Dissipation (watts) calculation assumes an LED case temperature of 85°C and an LED input power to output power conversion efficiency of 80%.
- Custom versions of this product are available upon request.
- Holes for mounting LED devices are available and supported by Cooliance. Please consult factory for mounting hole options.

# CPL50 Series Passive LED Cooler

## Thermal Performance Chart

